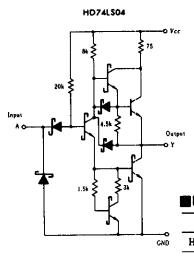
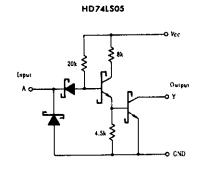
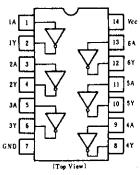
■CIRCUIT SCHEMATIC(1/6)

PIN ARRANGEMENT







■HD74LS05 RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
High level output voltage	Voн	_	_	5.5	v
Low level output current	l o _L	_		8	mA

ELECTRICAL CHARACTERISTICS ($Ta = -20 \sim +75^{\circ}$ C)

				HD74LS04		HD74LS05			F7	
Item	Symbol	Test Conditions		min	typ*	max	min	typ*	max	Unit
	ViH			2.0		_	2.0	_	-	v
Input voltage	VIL			<u> </u>		0.8	_	_	0.8	V
- MANER	Voн	$V_{CC} = 4.75 \text{V}, V_{IL} = 0.8 \text{V}, I_{OH} = -400 \mu\text{A}$		2.7	_	-		_	_	V
Output voltage		$V_{CC} = 4.75 \text{V}, V_{IH} = 2 \text{V}$	Io L = 8m A	_	_	0.5	_	_	0.5	- v
	Vol		IoL=4mA	-	_	0.4	_	_	0.4	
Output current	Іон	$V_{CC} = 4.75V, V_{IL} = 0.8V, V_{OH} = 5.5V$			-		_	_	100	μA
	Ith	$V_{CC} = 5.25 \text{V}, V_I = 2.7 \text{V}$		_	_	20	_	-	20	μA
Input current It		Vcc=5.25V, V1=0.4V		-		-0.4	_	<u> </u>	-0.4	mA
		$V_{CC} = 5.25 \text{V}, V_I = 7 \text{V}$		1 -	-	0.1	-		0.1	mА
Short-circuit output current	los	Vcc=5.25V		-20	_	- 100	_	_		mA
	Іссн	Vcc = 5.25V		<u> </u>	1.2	2.4	_	1.2	2.4	.4 mA
Supply current	Iccı			_	3.6	6.6	_	3.6	6.6	
Input clamp voltage	Vik	Vcc=4.75V, I _{IN} =-18mA			_	-1.5	_	Ī	-1.5	V

^{*} VCC=5V, Ta=25°C

ESWITCHING CHARACTERISTICS ($V_{CC}=5V$, $T_a=25^{\circ}C$)

Îtem	Symbol	T . O Pre	HI	D74LS04		HD74LS05			Unit
		Test Conditions	min typ max			min	typ	max	Onit
	t PLH	C15-F B9h0	1	9	15	1	17	32	
Propagation delay time	tphl .	$C_L = 15 \text{pF}, R_L = 2 \text{k } \Omega$	ı	10	15	-	15	28	ns

Note) Refer to Test Circuit and Waveform of the Common Item

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

Unit: mm

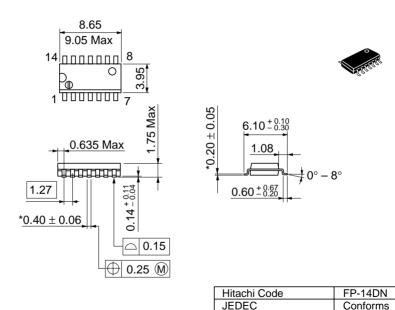


Weight (reference value)

0.23 g

*Dimension including the plating thickness
Base material dimension

Unit: mm



EIAJ

Weight (reference value)

Conforms

0.13 g

*Pd plating

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